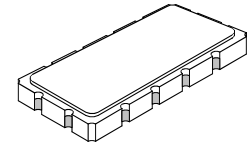


SF1056A

110.592 MHz
SAW Filter



SM13365-12

- *Designed for DECT and WLAN IF Applications*
- *Low Insertion Loss*
- *Excellent Size-to-Performance Ratio*
- *Hermetic 13.3 X 6.5 mm Surface-Mount Case*
- *Unbalanced Input and Output*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c		110.592			MHz
Passband	Insertion Loss at f_c 3 dB Passband	IL		8.5	10.0	dB
		BW_3		±576	±750	kHz
		GDV		<150	200	n _{SP-P}
Rejection	$f_c-3.4$ to $f_c-1.728$ and $f_c+1.728$ to $f_c+3.4$ MHz DC to $f_c-3.4$ and $f_c+3.4$ to 200 MHz Ultimate		28	40		dB
			40	>45		
				45		
Operating Temperature Range	T_A		-10		+60	°C

Impedance Matching to 50 Ω unbalanced	External L-C
Case Style	SM13365-12 13.3 X 6.5 mm Nominal Footprint
Lid Symbolization (YY=year, WW=week, S = Shift, ## = sequence code)	RFM, SF1056A, YYWWS##

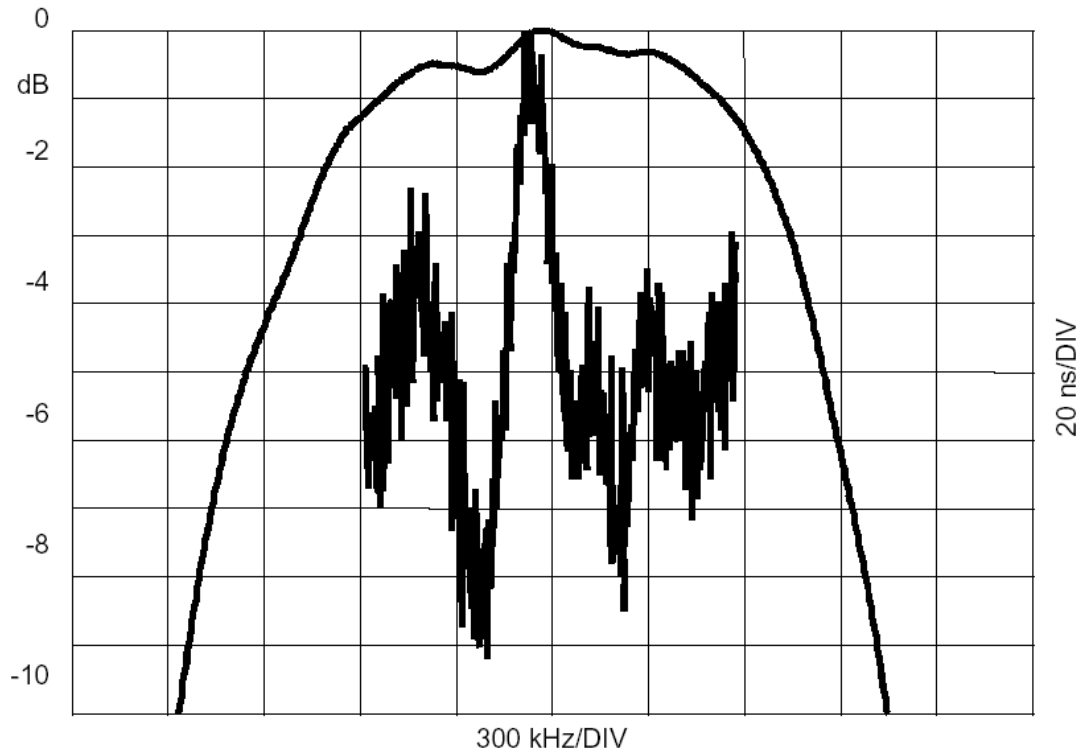
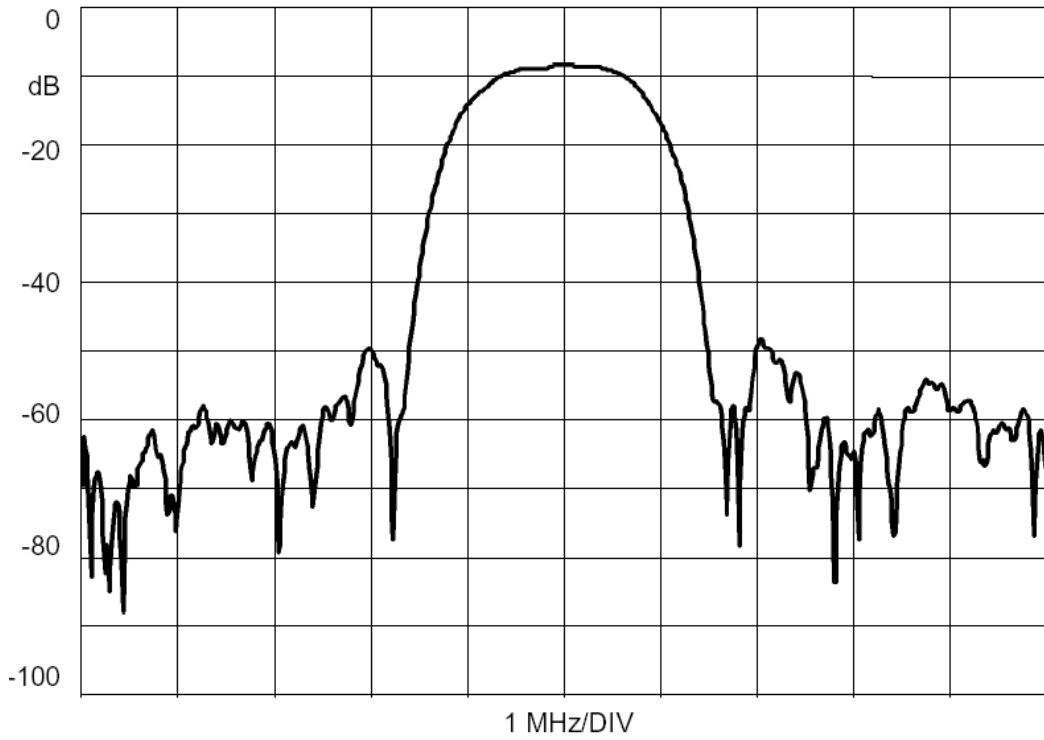
Electrical Connections

Connection	Terminals
Port 1 Hot	2
Port 1 Gnd Return	3
Port 2 Hot	8
Port 2 Gnd Return	9
Case Ground	All Others

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

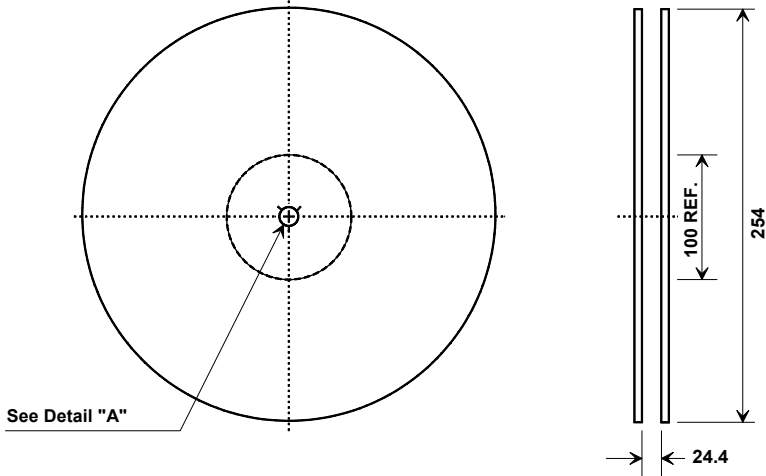
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

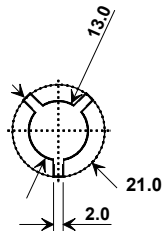


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA481

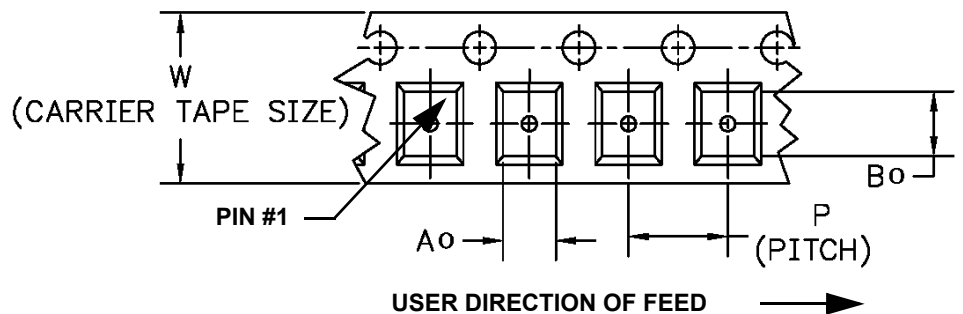
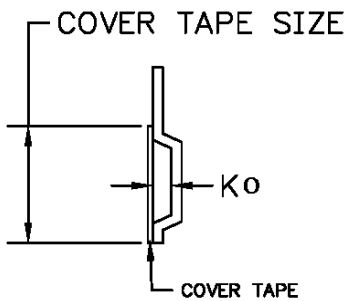


Reel Count:
7" = 250
13" = 1000



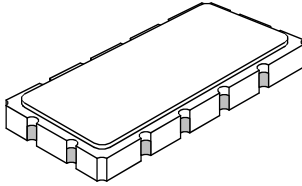
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	7.0 mm
Bo	13.8 mm
Ko	2.0 mm
Pitch	12.0 mm
W	24.0 mm



SM13365-12 Case

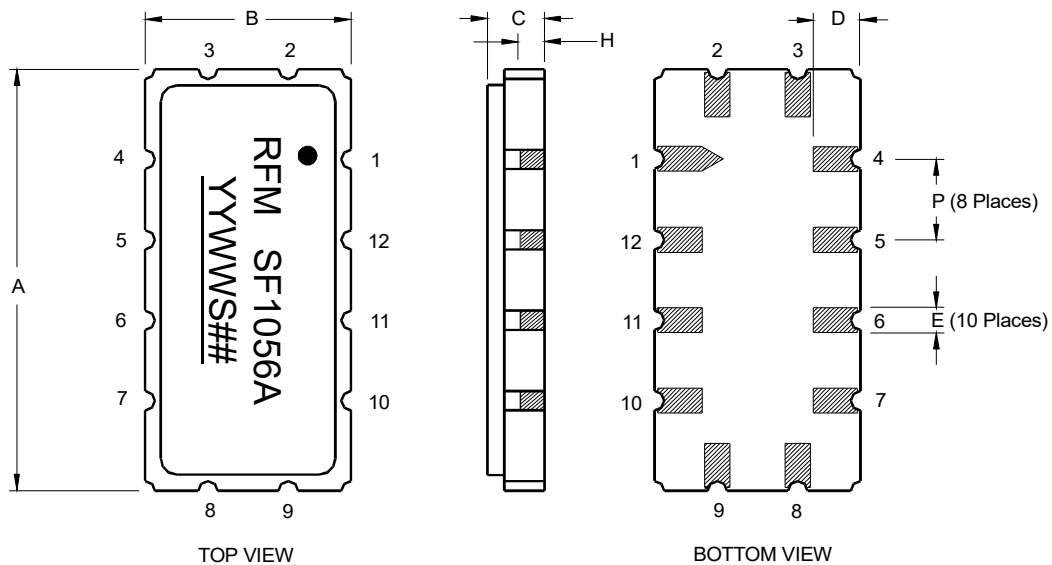
12-Terminal Ceramic Surface-Mount Case 13.3 x 6.5 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	13.08	13.31	13.60	0.515	0.524	0.535
B	6.27	6.50	6.80	0.247	0.256	0.268
C		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

Materials	
Solder Pad Termination	Au plating 30 - 60 μ inches (76.2-152 μ m) over 80-200 μ inches (203-508 μ m) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μ inches Thick
Body	Al ₂ O ₃ Ceramic

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	2
	Return or Input	3
Port 2	Output or Return	8
	Return or Output	9
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

